



B320AF/B330AF

3.0A SCHOTTKY BARRIER RECTIFIER

Product Summary

B320AF/B330AF

Product	V _{RRM} (V)	I _O (A)	V _{F(MAX)} (V) @ +25°C	I _{R(MAX)} (mA) @ +25°C
B320AF	20	3	0.50	0.20
B330AF	30	3	0.50	0.20

Description and Applications

The Schottky providing low V_F and excellent reverse leakage stability at high temperatures, this device is ideal for use in general rectification applications such as:

- **Boost Diodes**
- **Blocking Diodes**
- Recirculating Diodes

Features and Benefits

- Reduced Low Forward Voltage Drop (VF); Better Efficiency and **Cooler Operation**
- Reduced High-temperature Reverse Leakage; Increased Reliability against Thermal Runaway Failure in High **Temperature Operation**
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: SMAF
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band
- Weight: 0.036 grams (Approximate)

SMAF



Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
B320AF-13	SMAF	10,000/Tape & Reel
B330AF-13	SMAF	10,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



B3XXAF = Product Type Marking Code, ex: B320AF ⊃¦¦ = Manufacturers' Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 7 for 2017) WW = Week Code (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	B320AF	B330AF	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _{RM}	20	30	٧
Average Rectified Output Current	Io	3	3	Α
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	80		Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	85	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R _{eJC}	45	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

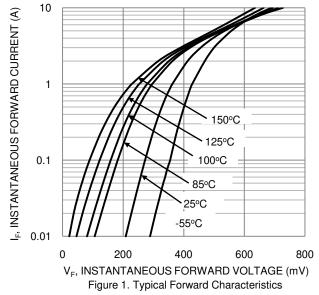
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

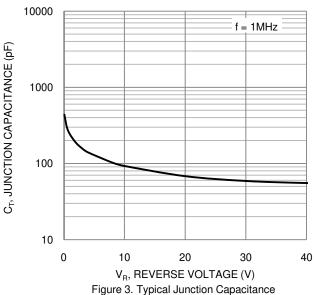
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage Drop		V _F	_ _	0.46 0.40	0.50 —	٧	I _F = 3A, T _J = +25°C I _F = 3A, T _J = +125°C
Leakage Current (Note 6)	B320AF B330AF	I _R	_ _ _	0.02 12 0.03 14.0	0.20 — 0.20 —	mA	$V_R = 20V, T_J = +25^{\circ}C$ $V_R = 20V, T_J = +125^{\circ}C$ $V_R = 30V, T_J = +25^{\circ}C$ $V_R = 30V, T_J = +125^{\circ}C$
Typical Capacitance		Ст	_	140	_	pF	$V_R = 4.0V$, $f = 1MHz$

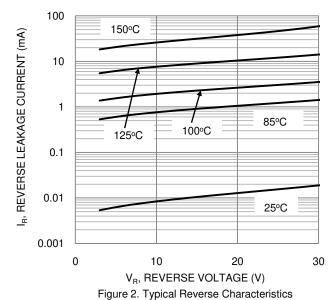
Notes:

- 5. Device mounted on FR-4 substrate, 0.4"*0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pad. 6. Short duration pulse test used to minimize self-heating effect.









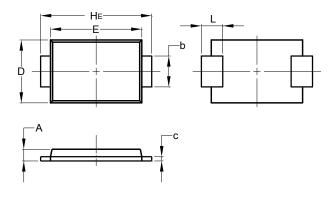
3.50 Note 5 3.00 I_F, DC FORWARD CURRENT (A) 2.50 2.00 1.50 1.00 0.50 0.00 25 50 75 100 125 150 T_A, AMBIENT TEMPERATURE (°C) Figure 4. DC Forward Current Derating



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMAF

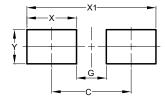


SMAF					
Dim	Min	Max			
Α	0.90	1.10			
b	1.25	1.65			
С	0.10	0.40			
D	2.25	2.95			
Е	3.95	4.60			
HE	4.80	5.60			
L	0.50	1.50			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SMAF



Dimensions	Value (in mm)		
С	4.00		
G	1.50		
Х	2.50		
X1	6.50		
Υ	1.70		



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